♦CHIP TYPE PART NUMBER



♦RADIAL LEAD TYPE PART NUMBER

Rated Voltage Series		Capacitance		Capacitance T	olerance	Option	Lead Forming	D×L Case Size
		↑		↑		*	↑	
Rated Voltage(V)	Code	Cap.(µF)	Code	Tolerance	Code		TA, KC,	6.3×8
25	25	220	220	±20%	M		CA etc	8×10 10×13
63	63	10	10					10/10
				Please ind	icate the a	above info	rmation, when o	rdering.
Example								
Long lead typeTaping type		35 50	PZA PZC	82 47	M M		Т8	8×12.5 10×13

*Option : Standard item is blank.

PACKAGING SPECIFICATION

♦V Chip Ty	ре			Q'ty(pcs)		Q'ty(pcs)		
SIZE (mm)	W3 (mm)	ΦC (mm)	Q'ty(pcs/reel)	Standard Shipping Carton Quantity (pcs/Box)	SIZE (mm)	LONG LEAD (BULK PACKAGE)	LEAD FORMING (BULK PACKAGE)	TAPING
φ6.3×6.1	18	382	1,000	5,000	φ6.3×8	1,000	1,000	2,000
φ6.3×8	18	382	900	4,500	φ8×8	1,000	1,000	1,000
φ8×10.5	26	382	500	2,000	φ8×9	1,000	1,000	1,000
φ8×12	26	382	400	1,600	φ8×10	1,000	1,000	1,000
φ8×15	26	382	350	1,400	φ8×12.5	1,000	1,000	1,000
φ10×10.5	26	382	500	2,000	φ10×9	1,000	1,000	500
φ10×12	26	382	400	1,600	φ10×10	1,000	1,000	500
φ10×15	26	382	250	1,000	φ10×13	1,000	1,000	500

Please refer to TAPING REEL for W3 and ϕ C.

There are some differences between actual package quantity and above list.

(mm)

♦ TAPING SPECIFICATIONS

♦DIMENSIONS





\$SPECIFICATION TABLE

Items		фF	3.3	φ8				φ10	% Tolerance
		φ6.3		8mm Height		9mm or more Height			Torcharioc
Taping code		Т5	ΤZ	ТА	Т7	TA	Τ7	Т8	
Applicable Fig. No.		Fig.2	Fig.1	Fig.1	Fig.2	Fig.1	Fig.2	Fig.2	
Dia. of lead	φd	0.45			0.6			±0.05	
Height of body	L	9.5				15.0			MAX
Distance from center to center of next body	Р	12.7							±1.0
Distance from center to center of next driving hole		12.7							±0.2
Distance between center of driving hole and lead	P1	5.1	3.85		4.6	3.85	4.6	3.85	±0.5
Distance between center of driving hole and body		6.35						±1.0	
Pitch of lead		2.5	5.	5.0		5.0	3.5	5.0±0.8	+0.8 -0.2
Width of mounting tape		18.0					±0.3		
Width of adhesive tape		5.0					MIN		
Distance between center of driving hole and mounting tape edge		9.0						±0.5	
Max. allowable distance between mounting and adhesive tape edges		1.5						MAX	
Distance between center of driving hole and bottom of body		17.5 2			20).0		18.5 +0.75 -0.5	±0.75
Distance between center of driving hole and clinch part of lead	Ho		16	5.0		16.0			±0.5
End of lead	L1	0.5				MAX			
Dia. of driving hole		4.0					±0.2		
Off alignment of body top		1.0						MAX	
Off alignment of body top		1.0						MAX	
Sum of thickness for mounting and adhesive tape without lead dia	t			0.6					±0.3
Quantity (pcs)		2000		1000			500		

 $\% \mbox{For the case that tolerance is specified individually, the value shall have the priority.$

Rubycon CONDUCTIVE POLYMER ALUMINUM SOLID ELECTROLYTIC CAPACITORS PZ-CAP

♦LEAD CUTTING FORMING SPECIFICATIONS

Rubycon provides lead-formed and lead-cut products to facilitate mounting on printed circuit boards, as well as products with leads specially processed (kink formed) for self supporting insertions to printed circuit boards.



Chip type capacitors TAPING DIMENSIONS



TAPING REEL



Reuseable reels are available according to your request.

Please consult in regard to establishing supply and withdrawal system.

Size φ8~φ10

1) Temperature at surface of capacitor shall not exceed T°C.

LEAD FREE TYPE REFLOW SOLDERING CONDITION

- 2) Period that temperature at surface of capacitor becomes more that 200°C and T1°C shall not exceed t and t1 seconds, respectively.
- 3) Preheat shall be made at 100°C~180°C and for maximum 120 seconds.

an	Series	Size	T(°C) ①	T₁(℃)	t(sec)	tı(sec)	Reflow cycle
	PAV	φ8	250	230	60	40	2
	PCV	φ10	260	230	60	40	1
n		φ6.3	250	230	60	40	2
	PEV	φ0.5	260	230	60	40	1
	PFV	PFV Ø8		230	60	40	2
		<i>ф</i> 10	260	230	60	40	1

4) Please ensure that the capacitor became cold enough to the room temperature before the second reflow.



①Peak temperature

②Time more than 200°C ⟨MAX⟩

(3)Time more than T₁ (MAX)

*Please contact us if the condition is over the maximum.

RECOMMENDED LAND SIZE

